



Appl. No. 10/712,708
Amdt. dated April 15, 2008 and re-submitted on July 18, 2008
Reply to Office Action dated January 29, 2008

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:

CHEN et al.

Application No: 10/712,708

Filed: November 12, 2003

For: HEAT DISSIPATION MODULE

) Group Art Unit: 3744

) Examiner: CIRIC, L.

) Docket No: JLINP174/TLC

) Date: July 18, 2008

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited
with the United States Postal Service as First Class Mail in an
envelope addressed to: Commissioner for Patents, Alexandria, VA
22313-1450 on July 18, 2008.

Kathi L. Montanez
Kathi L. Montanez

AMENDMENT

Honorable Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Dear Sir:

This paper is in response to the Official Action mailed on January 29, 2008,
and is a resubmission in response to the Notice of June 18, 2008, setting a due date of
July 18, 2008. This response is timely. Applicant respectfully submits comments in
connection with the above-named application.

Amendments to the claims are reflected in the listing of claims which begin on
page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.